F-26

NJ72 Process

Silicon Junction Field-Effect Transistor

VHF/UHF Amplifier

Absolute maximum ratings at TA = 25°C

Gate Current, Ig 10 mA Operating Junction Temperature, Tj $+150^{\circ}$ C Storage Temperature, Ts -65° C to $+175^{\circ}$ C

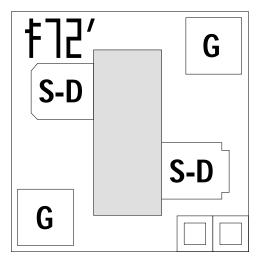
Devices in this Databook based on the NJ72 Process.

Datasheet

IFN5564, IFN5565 IFN5566 J308, J309 J308, J309 J310

Datasheet

U308, U309 U430, U431 VCR2N



Die Size = 0.020" X 0.020" All Bond Pads = 0.004" Sq. Substrate is also Gate.

At 25°C free air temperature:			NJ72 Process						
Static Electrical Characteristics		Min	Тур	Max	Unit	Test Conditions			
Gate Source Breakdown Voltage	V _{(BR)GSS}	- 25	- 40		V	$I_G = -1 \mu A$, $V_{DS} = \emptyset V$			
Reverse Gate Leakage Current	I _{GSS}		- 10	- 100	pА	$V_{GS} = -15 V$, $V_{DS} = \emptyset V$			
Drain Saturation Current (Pulsed)	I _{DSS}	5		90	mA	V _{DS} = 15 V, V _{GS} = Ø V			
Gate Source Cutoff Voltage	V _{GS(OFF)}	- 1		- 5.5	V	V _{DS} = 15 V, I _D = 1 nA			

Dynamic Electrical Characteristics

Forward Transconductance	9 _{fs}	22	mS	$V_{DS} = 15 V$, $V_{GS} = \emptyset V$	f = 1 kHz
Drain Source ON Resistance	r _{ds(on)}	40	Ω	I _D = 1 mA, V _{GS} = ØV	f = 1 kHz
Input Capacitance	C _{iss}	6.5	pF	$V_{DS} = \emptyset V$, $V_{GS} = -10 V$	f = 1 MHz
Feedback Capacitance	C _{rss}	2.5	pF	$V_{DS} = \emptyset V$, $V_{GS} = -10 V$	f = 1 MHz

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